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(54) Title: FIELD ETCH TO ENHANCE IMAGE SHARPNESS OF AUGMENTED REALITY WAVEGUIDE COMBINERS

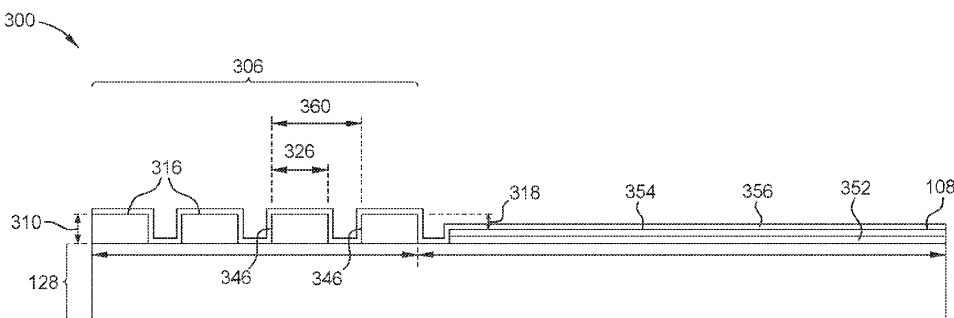


FIG. 3

(57) Abstract: The present disclosure provides waveguides and methods of forming thereof. The waveguides include a plurality of gratings. The plurality of gratings include grating structures disposed over a waveguide substrate. The grating structures include a grating depth. A waveguide layer is disposed over the waveguide substrate between each of the plurality of gratings and an edge of the waveguide substrate. The waveguide layer has an etch depth. The etch depth is less than the grating depth.



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